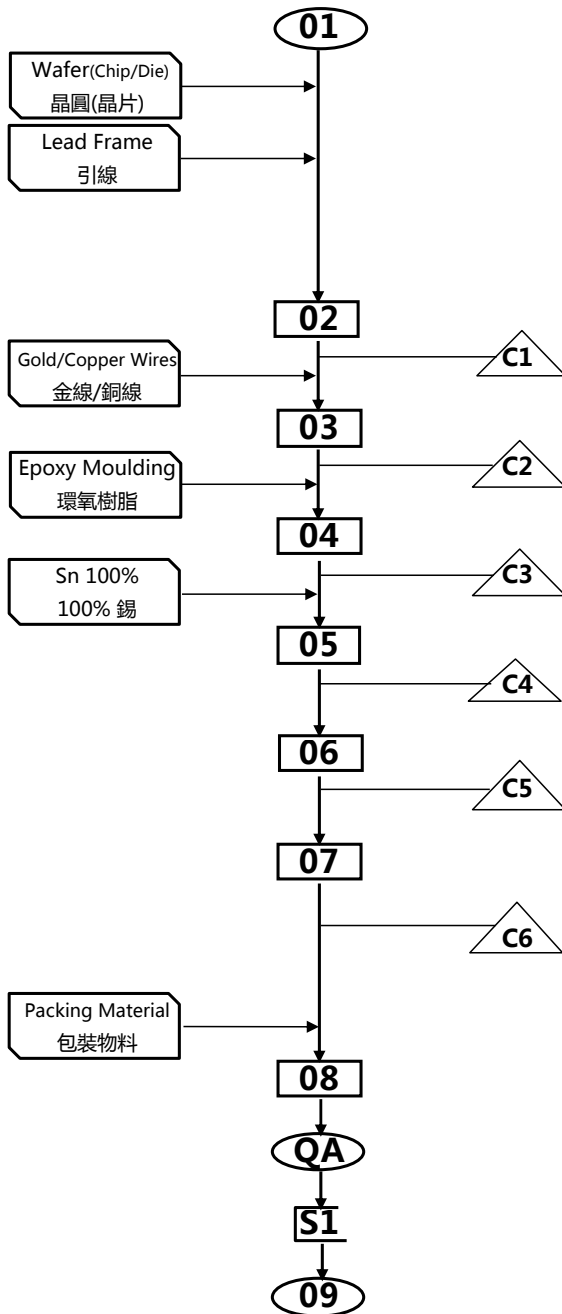


DIODES / TRANSISTORS DIE BONDING 二極管、三極管固晶

PROCESS FLOW CHART FOR EUTECTIC WIRE BONDING PROCESS PRODUCTS  
共晶焊線工藝產品工序流程圖 (SOT23, SOD323)



PROCESS DESCRIPTION

流程說明：

01	<b>MATERIAL INCOMING INSPECTION</b> 來料檢查
02	<b>EUTECTIC DIE BONDING</b> 共晶固晶 (晶片焊接)
03	<b>WIRE BONDING</b> 引線鍵合 (焊線焊接)
04	<b>MOULDING &amp; TRIMMING</b> 注塑及修剪水口
05	<b>SURFACE FABRICATION</b> 表面加工
06	<b>CUTTING &amp; FORMING</b> 切割及成型
07	<b>100% ELECTRICAL TESTING, LASER MARKING &amp; TAPING</b> 100% 電性測試、激光法標記及上帶
08	<b>PACKING</b> 包裝
09	<b>FINAL INSPECTION BEFORE DISPATCHING</b> 交貨前最終檢查
QA	<b>QUALITY ASSURANCE</b> 品質保證檢查
S1	<b>STORAGE</b> 倉儲
C1	<b>QUALITY MONITORING AND CONTROL(IPQC) OF DIE BONDING</b> 晶片焊接過程品質監測及控制
C2	<b>QUALITY MONITORING AND CONTROL(IPQC) OF WIRE BONDING</b> 焊線焊接過程品質監測及控制
C3	<b>QUALITY MONITORING AND CONTROL(IPQC) OF MOULDING</b> 注塑過程品質監測及控制
C4	<b>QUALITY INSPECTION AND CONTROL OF SURFACE FABRICATION</b> 表面加工品質檢查及控制
C5	<b>QUALITY MONITORING AND CONTROL(IPQC) OF CUTTING &amp; FORMING</b> 切割及成型過程品質監測及控制
C6	<b>QUALITY MONITORING AND CONTROL(IPQC) OF TESTING, MARKING &amp; TAPING</b> 測試、標記及上帶過程品質監測及控制

	Operation 操作		Inspection 檢查
	Storage 儲存		Material 材料
	Quality Monitoring and Control 品質監測及控制		Outsourcing Process 外包工序